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cont

wh rein the second chip is fixed, at the second chip one side, to the interposer substrate second surface via the adhesive sheet,

wherein the first chip reverse side is fixed to the second chip reverse side,
and

wherein the second electrode for wiring is exposed from the side of the interposer substrate at the interposer substrate second through the adhesive sheet small hole and the adhesive sheet through-hole.

REMARKS

Claim 2 has been canceled. Claims 3, 4, and 8 have been amended for improved clarity and to better protect the invention. Reexamination of the amended application respectfully is requested.

Respectfully submitted,

December 2, 2002
Date



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AMENDMENT

(09/912,064)

VERSION OF MARKED-UP CLAIMS

1. (Amended) A semiconductor chip package comprising:

- a first integrated semiconductor chip having a one side and a reverse side;
- a first electrode for wiring formed on the first chip one side;
- a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface;
- a second integrated semiconductor chip having a one side and a reverse side, the second chip one side facing the [interposer substrate] first surface, the second chip being formed on the interposer substrate first surface; and
- a second electrode for wiring formed on the second chip one side so as to be exposed through the interposer substrate through-hole, the second electrode to be wired through the through-hole to external terminals on the interposer substrate second surface, the first chip being [formed] provided on the second chip reverse side with the first chip reverse side facing the second chip reverse side.

3. (Amended) A semiconductor chip package, comprising:

- a first integrated semiconductor chip having a first chip size and having a one side and a reverse side;
- a first electrode for wiring formed on the first chip one side;
- a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first chip being [integrally] mounted to the second chip with the second chip reverse side opposing the first chip reverse side;

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a second electrode for wiring formed on the second chip one side;

a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface, the through-hole being larger than the [first and second chip sizes] second chip size;

an adhesive sheet having opposite first and second surfaces, the adhesive sheet being formed of a sheet-shaped adhesive material provided on the interposer substrate at the interposer substrate first surface so as to cover the through-hole, the adhesive sheet second surface being exposed through the through-hole from a side of the interposer substrate at the interposer substrate second surface,

wherein the second chip reverse side is fixed to the adhesive sheet second surface, and the first chip reverse side is fixed to the adhesive sheet first surface so as to oppose the second chip reverse side at a position at which the second chip is fixed, whereby the second electrode can be wired to any external terminals on the interposer substrate second surface.

4. (Amended) A semiconductor chip package, comprising:

a first integrated semiconductor chip having a first chip size and having a one side and a reverse side;

a first electrode for wiring formed on the first chip one side;

a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first chip being [integrally] mounted to the second chip with the second chip reverse side opposing the first chip reverse side;

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an interposer substrate having a through-hole, ~~the through-hole~~ being smaller than the first chip size and larger than the second chip size,

wherein the first chip is fixed to the interposer substrate first surface at a portion of the first chip reverse side, such that the through-hole is covered by the first chip, and

wherein the second chip reverse side is fixed to the first chip reverse side, the first chip reverse side being exposed through the through-hole from a side of the interposer substrate at the interposer substrate second surface.

8. (Amended) A semiconductor chip package, comprising:

a first integrated semiconductor chip having a first chip size and having a one side and a reverse side;

a first electrode for wiring formed on the first chip one side;

a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first chip being [integrally] mounted to the second chip with the second chip reverse side opposing the first chip reverse side;

a second electrode for wiring formed on the second chip one side;

a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface;

and

an adhesive sheet formed of sheet-shaped adhesive material at the interposer substrate first surface so as to cover the through-hole, the adhesive sheet being larger

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than the second chip size and having a hole smaller than the second chip size,
[second chip size than the second chip size,]

wherein the second chip is fixed, at the second chip one side, to the interposer
substrate second surface via the adhesive sheet,

wherein the first chip reverse side is fixed to the second chip reverse side,
and

wherein the second [chip] electrode for wiring is exposed from the side of the
interposer substrate at the interposer substrate second [at a reverse surface side of the
surface] through the adhesive sheet small hole and the adhesive sheet through-hole.